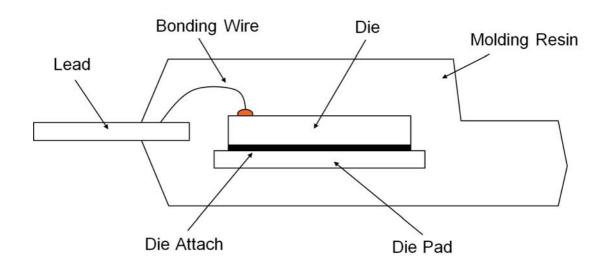


1. Package Information

Package Name	TO220CP-3
Туре	ТО
Pin Count	3
Outline Dimension	-
Drowing No.	4 40
Package Weight [g]	1.42
Lead Finish	Pure Tin
MSL Level	N/A

2. Package Structure



TO220CP-3

3. Packing Specification

3.1 Packing form, Quantity, PIN1 Orientation

	Tape&Ree
[pcs]	500
	E2
	[pcs]

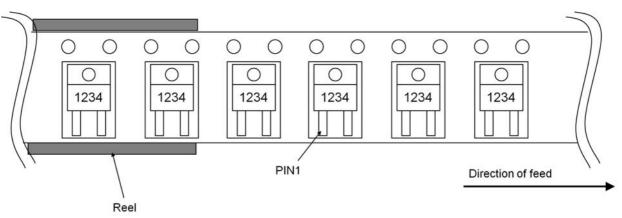


Fig.1 Quadrant Assignments for PIN 1 Orientation in Tape

3.2 Use material

ltem	Material
Embossed carrier tape	PS
Cover tape	PET+PE
Reel	PS
Air cap	-
Unit box	Cardboard
Shipping box	Cardboard

3.3 Leader specification

No component pockets are 640 mm or more.

3.4 Trailer specification

No component pockets are 160 mm or more. Tape is free from reel.

3.5 Peelback strength

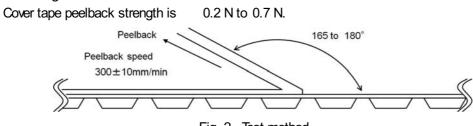
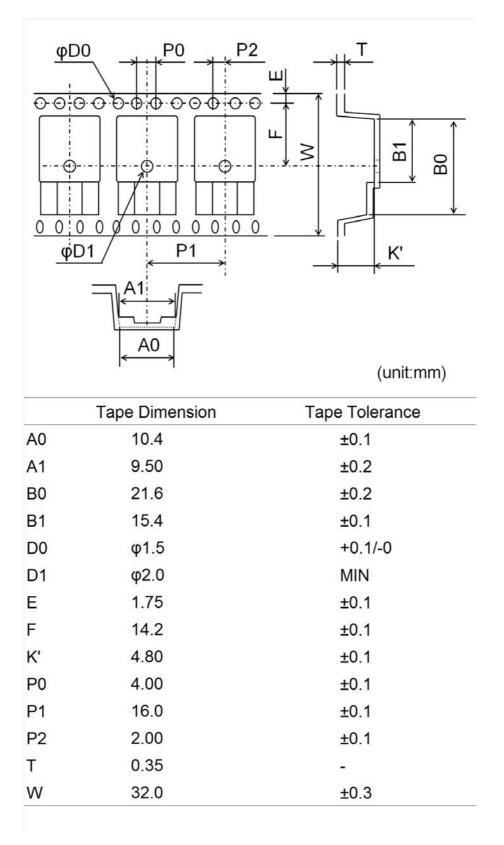


Fig. 2 Test method

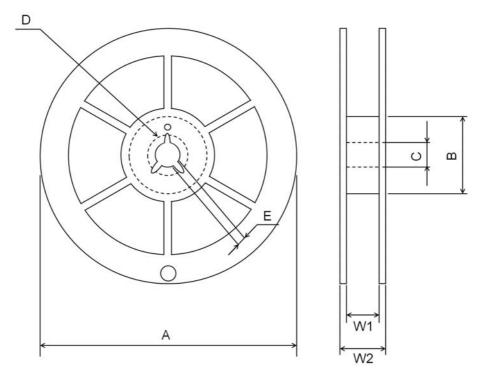
3.6 Missing Ics

- (1) No consecutive dropouts.
- (2) A maximun 0.1 % of specified number of products in each packing may be missing.

3.7 Tape and Reel Specification

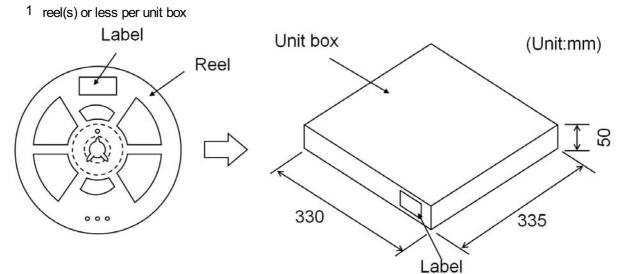


3.7.2 Reel Dimension



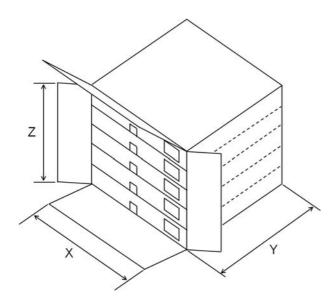
		(unit:mm)
	Reel Dimension	Reel Tolerance
А	330	±2.0
В	80	±1.0
С	13	±0.2
D	21	±0.8
Е	2	±0.5
W1	33.5	±1.0
W2	37.5	±1.0

3.8 Packing Method



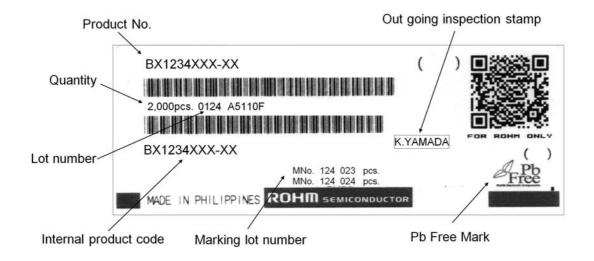
3.9 Packing Style

5 unit boxes or less per shipping box

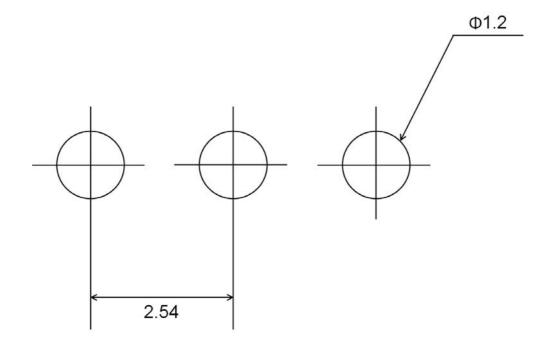


	(unit:	mm)
Shipp	oing Box Dimensio	n
Х	347	
Y	353	
Z	287	

3.10 Label Specification



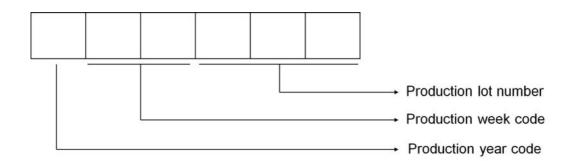
4. Footprint dimensions



(unit:mm)

In actual design, please optimize in accordance with the situation of your board design and soldering condition.

5. Marking Specification



6. Storage conditions

6.1 Storage environment

|--|

	Min.	Max.	Unit
Temperature	5	30	C°
Humidity	40	70	% RH
			,0.2

6.2 Storage period

	Min.	Max.	Unit
Storage period	-	1	year

7. Soldering conditions

7.1 Recommended condition for wave soldering

Preheating temperature	:	120 °C t	o 150 °C
Preheating time	:	60 sec	MAX
Soldering temperature	:	260 °C ±	: 3 ℃
Soldering time	:	12 sec	MAX

Notes for wave soldering

(1)Soldering time is provided for total soldering time in case of dual wave soldering.

(2) Do not use other soldering methods with wave soldering.

(3) Recommend to clean the board to eliminate flux, solder waste,

and other impurities for reliability, after soldering.

(4) Optimize soldering condition to prevent solder bridging.

7.2 Recommended condition for solder iron

Solder iron temperature	:	380	°C or less
Mounting time	:	4	sec or less

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3)	Although ROHM is continuously working to improve product reliability and quality, semicon- ductors can break down and malfunction due to various factors. Therefore, in order to prevent personal injury or fire arising from failure, please take safety measures such as complying with the derating characteristics, implementing redundant and fire prevention designs, and utilizing backups and fail-safe procedures. ROHM shall have no responsibility for any damages arising out of the use of our Poducts beyond the rating specified by ROHM.
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